

AMENDMENTS

IN THE SPECIFICATION:

Page 1, after the title, insert the following paragraph:

--RELATED APPLICATION

This application is a national stage application of International Application No. PCT/DE02/00067 filed January 9, 2002, which is entitled "PHOTODIODE ARRAY AND METHOD FOR ESTABLISHING A LINK BETWEEN A FIRST SEMICONDUCTOR ELEMENT AND A SECOND SEMICONDUCTOR ELEMENT", which was not published in English, which is hereby incorporated by reference in its entirety.--

Page 1, line 7, Please add **--FIELD OF THE INVENTION--**.

Page 1, line 17: Please add **--BACKGROUND OF THE INVENTION--**.

Page 3, line 15: Please add **--SUMMARY OF THE INVENTION--**.

Page 3, lines 16-22: Please replace the paragraph with the following paragraph:

Therefore, the present invention is based on ~~the object~~ an aspect of providing a photodiode arrangement and a method for producing a connection between a first semiconductor component and a second semiconductor component which make it possible to connect the semiconductor components using standard processes and, at the same time, in an economical and effective manner.

Page 3, lines 24-28: Please replace the paragraph with the following paragraph:

This ~~object~~ present invention is achieved ~~according to the invention~~ by means of a photodiode arrangement having the features of ~~claim 1 and a method having the~~

~~features of claim 8~~the independent claim or claims. Preferred and advantageous refinements of the invention are specified in the subclaims.

Page 4, lines 1-7: Please replace the paragraph with the following paragraph:

In a second aspect, the invention provides a method for producing a connection between a first semiconductor component and a second semiconductor component which have a different outer contour. In particular, the method serves for connecting a photodiode to a submount for the production of a photodiode arrangement ~~in accordance with claim 1~~.

Page 4, lines 9-30: Please replace the paragraph with the following paragraph:

The method ~~has the following steps of~~comprises:

- a) producing a multiplicity of first semiconductor components on a first wafer,
- b) producing a multiplicity of second semiconductor components on a second wafer, in this case
- c) providing a metallization on the first semiconductor components of the first wafer,
- d) providing a metallization on the second semiconductor components of the second wafer,
- e) forming trenches in the first and/or the second semiconductor components, then
- f) connecting the two wafers by eutectic bonding of the respective metallizations, the resulting wafer composite having a front side and a rear side, then
- g) singulating the front side of the wafer composite in accordance with a first outer contour of the first semiconductor components to be singulated, only the first wafer being severed, and subsequently
- h) singulating the rear side of the wafer composite in accordance with a second outer contour of the second semiconductor components to be singulated, only the second wafer being severed.

Page 6, line 18: Please add --**BRIEF DESCRIPTION OF THE DRAWINGS**--.

Page 7, line 11: Please add --**DETAILED DESCRIPTION OF THE INVENTION**--.